	Hits	Search Text	DBs
1	4	(((dielectric or substrate) near3 (Cu or copper or metal$3 or conductive)) same ((photoresist or resist) near4 first) same (pattern$4 or (expos$4 near5 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same (conductive near4 bump) same circuit$5) and ((second near4 (photoresist or resist)) same (pattern$4 or (expos$4 near4 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same dielectric) and ((second near4 (metal$4 or conductive)) same dielectric same (conductive near3 bump) same interconnect$4)	US-PGPUB; USPAT
2	4	(pluralit$4 or multip$3) near4 (conductive near4 bump) and interconnect$4 and (first near4 (metal$4 or conductive)) same (second near4 (conductive or metal$4)) same ((first or initial) near5 (photoresist or resist)) same (pattern$4 or (expos$4 near6 develop$4 or mask) same (conductive near3 bump)) and ((second near4 (photoresist or resist)) same expos$4 same develop$4) and ((third near4 (photoresist or resist)) same ((expos$4 near6 develop$5) or mask or pattern$5) same (etch$4 near5 (metal$4 or conductive)) same (first or second) same dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	8	(("3767398") or ("3960561") or ("4209355") or ("4372804") or ("4983252") or ("5092032") or ("5200026") or ("5492233")).PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
4	4	(((dielectric or substrate) near3 (Cu or copper or metal$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern$4 or (expos$4 near5 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same ((conductive or metal$4) near4 bump) same circuit$5) and ((second near4 (photoresist or resist)) same (pattern$4 or (expos$4 near4 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same dielectric) and ((second near4 (metal$4 or conductive)) same dielectric same ((conductive or metal$4) near3 bump) same interconnect$4)	US-PGPUB; USPAT
5	4	(((dielectric or substrate) near3 (Cu or copper or metal$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern$4 or (expos$4 near5 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same ((conductive or metal$4) near4 bump) same circuit$5) and ((second near4 (photoresist or resist)) same (pattern$4 or (expos$4 near4 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same dielectric) and ((second near4 (metal$4 or conductive)) same dielectric same ((conductive or metal$4) near3 bump) same interconnect$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	4	((pluralit$4 or multip$3) near4 ((conductive or metal$3) near4 bump)) and interconnect$4 and (first near4 (metal$4 or conductive or Cu or copper)) same (second near4 (conductive or metal$4 or aluminum or Al)) same ((first or initial) near5 (photoresist or resist or photosensitive)) same (pattern$4 or (expos$4 near6 develop$4 or mask) same ((conductive or metal$4) near3 bump)) and ((second near4 (photoresist or resist)) same expos$4 same develop$4) and ((third near4 (photoresist or resist)) same ((expos$4 near6 develop$5) or mask or pattern$5) same (etch$4 near5 (metal$4 or conductive)) same (first or second) same	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

		dielectric)	

	Hits	Search Text	DBs
7	4	(((dielectric or substrate) near3 (Cu or copper or metal$3 or conductive)) same ((photoresist or resist or photosensitive) near4 first) same (pattern$4 or (expos$4 near5 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same ((conductive or metal$4) near4 bump) same circuit$5) and ((second near4 (photoresist or resist)) same (pattern$4 or (expos$4 near4 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same dielectric) and ((second near4 (metal$4 or conductive)) same dielectric same ((conductive or metal$4) near3 bump) same interconnect$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	4	(((dielectric or substrate or wafer) near3 (Cu or copper or metal$3 or conductive)) same ((photoresist or resist) near4 first) same (pattern$4 or (expos$4 near5 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same (conductive near4 (land or bump)) same (line or circuit$5 or (conduct$5 near3 track))) and ((second near4 (photoresist or resist)) same (pattern$4 or (expos$4 near4 develop$4) or mask) same (etch$4 near5 (metal$4 or conductive)) same dielectric) and ((second near4 (metal$4 or conductive)) same dielectric same (conductive near3 (land or bump)) same interconnect$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
9	4	((pluralit$4 or multip$3) near4 ((conductive or metal$3) near4 (land or bump))) and interconnect$4 and (first near4 (metal$4 or conductive or Cu or copper)) same (second near4 (conductive or metal$4 or aluminum or Al)) same ((first or initial) near5 (photoresist or resist or photosensitive)) same (pattern$4 or (expos$4 near6 develop$4 or mask) same ((conductive or metal$4) near3 (land or bump))) and ((second near4 (photoresist or resist)) same expos$4 same develop$4) and ((third near4 (photoresist or resist)) same ((expos$4 near6 develop$5) or mask or pattern$5) same (etch$4 near5 (metal$4 or conductive)) same (first or second) same dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB